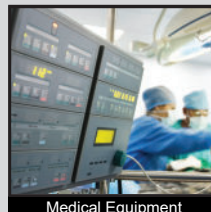
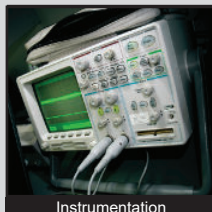
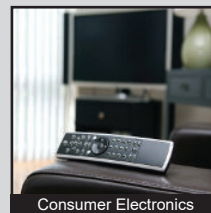
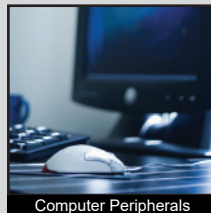
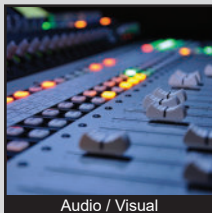


RT3301 SERIES TACT SWITCH

ANTI-VANDAL SWITCHES
 DETECTOR SWITCHES
 DIP SWITCHES
 KEYLOCK SWITCHES
 NAVIGATION SWITCHES
 PUSHBUTTON SWITCHES
 ROCKER SWITCHES
 ROTARY SWITCHES
 SLIDE SWITCHES
 SNAP ACTION SWITCHES
TACTILE SWITCHES
 TOGGLE SWITCHES
 CAP OPTIONS



APPLICATIONS / MARKETS



RoHS

SPECIFICATIONS

Electrical Rating: 50mA, 12VDC
Contact Resistance: 100mΩ Max. (Initial)
Insulation Resistance: 100MΩ Min. at 100VDC
Dielectric Strength: 250VAC for 1 Minute
Life Cycles: 100,000 cycles
Operating Temperature: -40°C to 85°C
Travel: 0.25mm +0.2mm / - 0.1mm
Contact Material: Silver
Operating Force: 260gf ± 50gf
Function: SPST, Off-(On)
Packaging: Tape and Reel, 1,000 pcs/reel

FEATURES & BENEFITS

- Top actuated, reverse surface mount design
- 6.00 x 6.00mm size
- 260 gram actuation force
- Up to 100,000 cycle life expectancy
- Tape and Reel packaging

PART NUMBER CONFIGURATOR

Series <input type="text" value="R"/> <input type="text" value="T"/> <input type="text" value="3"/> <input type="text" value="3"/> <input type="text" value="0"/> <input type="text" value="1"/> RT3301	Actuator Height <input type="text" value="A"/> A - 5.3mm	Actuation Force <input type="text" value="F"/> <input type="text" value="2"/> <input type="text" value="6"/> <input type="text" value="0"/> F260 - 260gf	Contact Plating <input type="text" value="Q"/> Q - Silver
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Specifications subject to change without notice 7.1.2023



E-SWITCH®

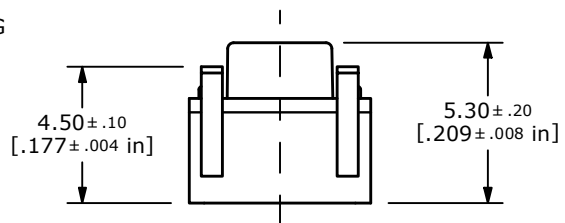
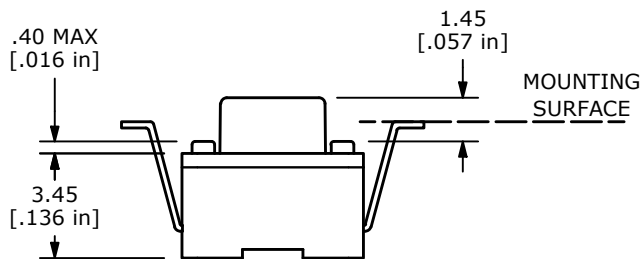
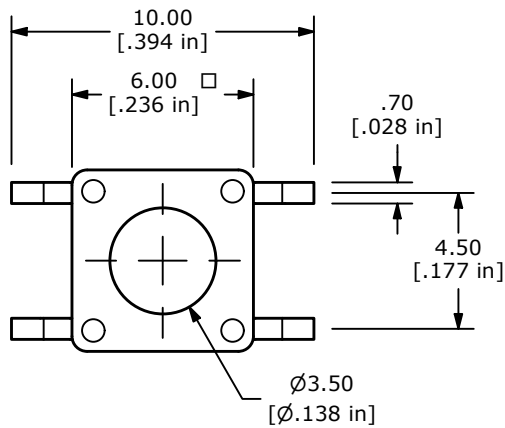
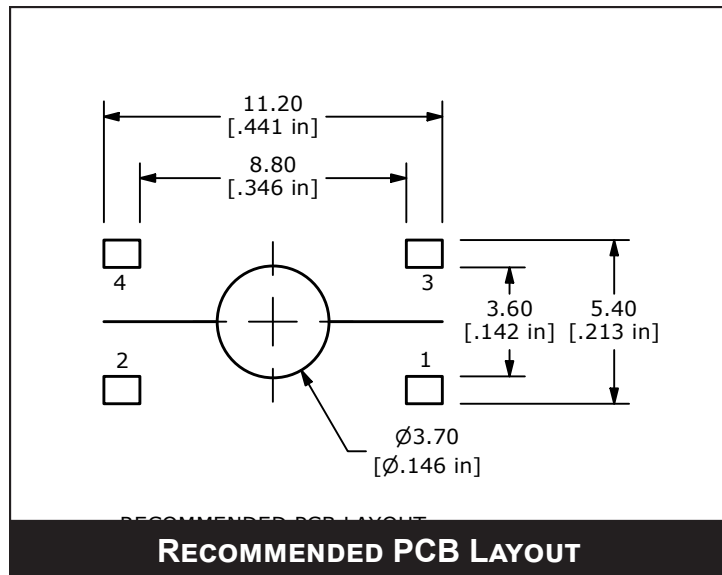
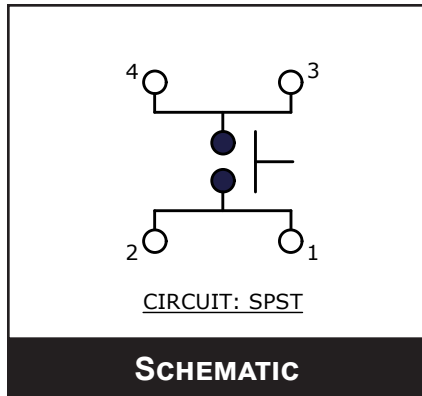
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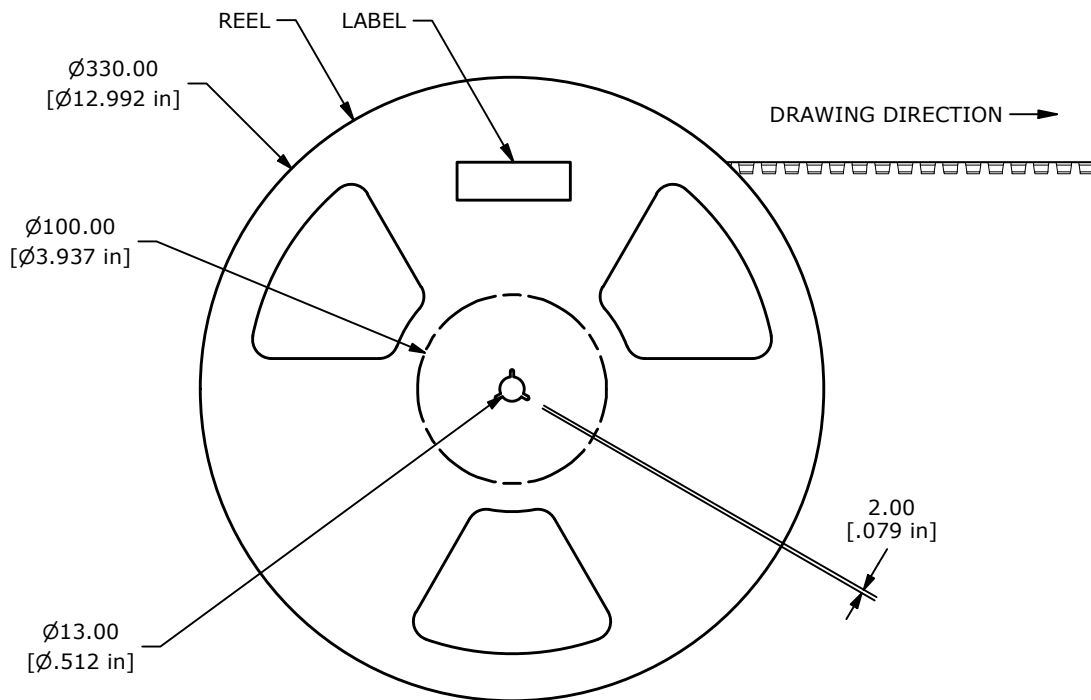
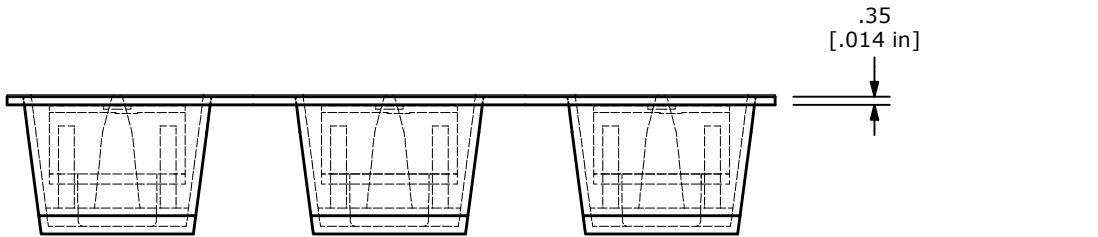
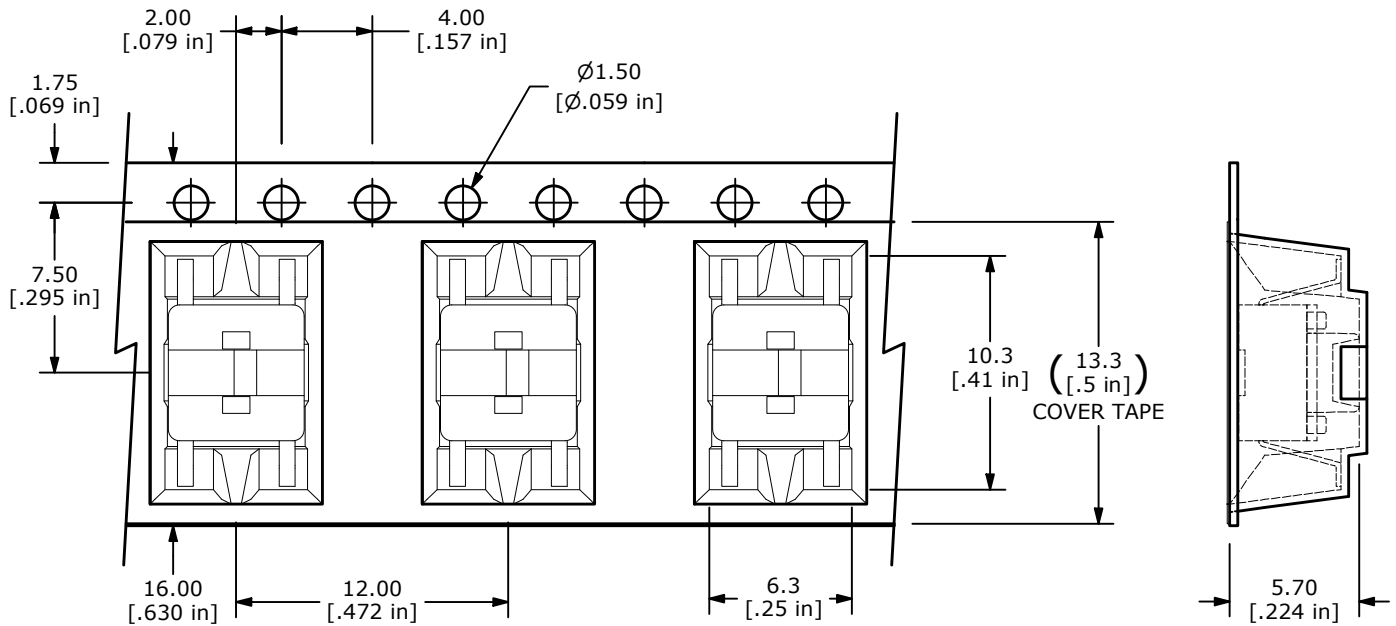
RT3301 SERIES TACT SWITCH

BODY DIMENSIONS



RT3301 SERIES TACT SWITCH

BODY DIMENSIONS TAPE AND REEL



RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C/second max.	3 °C/second max.
Preheat -Temperature Min ($T_{s_{min}}$) -Temperature Max ($T_{s_{max}}$) -Time ($t_{s_{min}}$ to $t_{s_{max}}$)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-180 seconds
Time Maintained above: -Temperature (T_L) -Time (t_L)	183 °C 60-150 seconds	217 °C 60-150 seconds
Time within 5 °C of actual Peak Temperature (t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

